

17235 U.S. PTO  
07/21/03

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application of: Leonard Forbes et al.

Title: STRAINED SEMICONDUCTOR BY FULL WAFER BONDING

Attorney Docket No.: 1303.109US1

17507 U.S. PTO  
10/623788  
07/21/03

**PATENT APPLICATION TRANSMITTAL**

**MAIL STOP PATENT APPLICATION**

Commissioner for Patents

P.O.Box 1450

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We are transmitting herewith the following attached items and information (as indicated with an "X"):

- ☒ Return postcard.
- ☒ Utility Patent Application under 37 CFR 1.53(b) comprising:
  - ☒ Specification (47 pgs, including claims numbered 1 through 65 and a 1 page Abstract).
  - ☒ Formal Drawing(s) (18 sheets).
  - ☒ **Signed Declaration** (5 pgs).
  - ☒ Signed Power of Attorney (1 pg).
  - ☒ Check in the amount of \$2316.00 to pay the filing fee.
- ☒ Assignment of the invention to Micron Technology, Inc. (4 pgs) and Recordation Form Cover Sheet.
- ☒ Check in the amount of \$40.00 to pay the Assignment recording fee.

The filing fee has been calculated below as follows:

	No. Filed	No. Extra	Rate	Fee
TOTAL CLAIMS	65-20	45	x 18.00 =	<b>\$810.00</b>
INDEPENDENT CLAIMS	12-3	9	x 84.00 =	<b>\$756.00</b>
[ ] MULTIPLE DEPENDENT CLAIMS PRESENTED				<b>\$0.00</b>
BASIC FEE				<b>\$750.00</b>
<b>TOTAL</b>				<b>\$2316.00</b>

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